

Description

The DIODES™ 74LVC2G34 is a dual buffer gate with standard push-pull outputs. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down.

The gate performs the positive Boolean function:

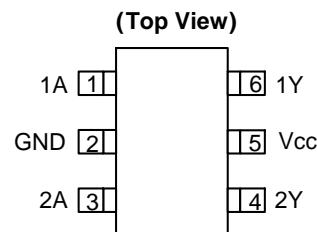
$$Y = A$$

Features

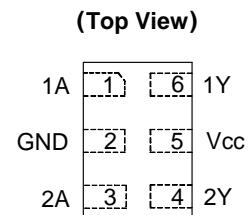
- Wide Supply Voltage Range from 1.65V to 5.5V
- $\pm 24\text{mA}$ Output Drive at 3.0V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Tested per JESD 22
- Exceeds 2000V Human Body Model (A114)
- Exceeds 1000V Charged Device Model (C101)
- Latch-up Exceeds 100mA per JESD 78, Class I
- X2-DFN1409-6 Package Designed as a Direct Replacement for Chip Scale Packaging
- Range of Package Options SOT26, SOT363, X1-DFN1010-6 (Type B), X2-DFN1010-6, X2-DFN1409-6, and X2-DFN1410-6
- Leadless Packages Named per JESD30E
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative.**

<https://www.diodes.com/quality/product-definitions/>

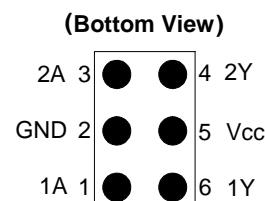
Pin Assignments



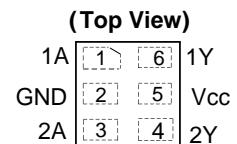
SOT26/SOT363



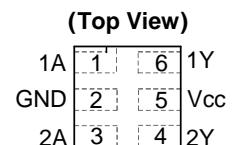
X2-DFN1410-6



X2-DFN1409-6
Chip Scale
Alternative



X1-DFN1010-6 (Type B)



X2-DFN1010-6

Applications

- Voltage level shifting
- General purpose logics
- Power down signal isolations
- Wide array of products such as:
 - PCs, networking, notebooks, netbooks, tablets
 - Computer peripherals, hard drives, SSD, CD/DVD ROM
 - TV, DVD, DVR, set-top boxes
 - Cell phones, personal navigations/GPS
 - MP3 players, cameras, video recorders

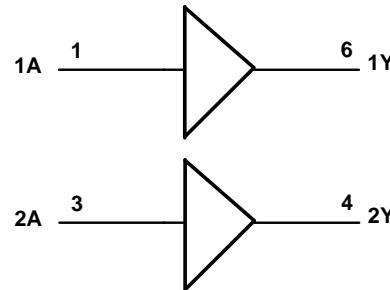
Notes:

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Pin Descriptions

Pin Number	Pin Name	Function
1	1A	Data Input
2	GND	Ground
3	2A	Data Input
4	2Y	Data Output
5	Vcc	Supply Voltage
6	1Y	Data Output

Logic Diagram



Function Table

Inputs	Output
A	Y
H	H
L	L

Absolute Maximum Ratings (Notes 4 & 5) (@TA = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
Vcc	Supply Voltage Range	-0.5 to +6.5	V
Vi	Input Voltage Range	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High or Low State	-0.3 to Vcc+0.5	V
I _{IK}	Input Clamp Current Vi < 0	-50	mA
I _{OK}	Output Clamp Current Vo < 0	-50	mA
I _O	Continuous Output Current	-50	mA
—	Continuous Current through V _{DD} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Notes:

4. Stresses greater than those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to *Absolute Maximum Ratings* for extended periods can affect device reliability.
5. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 6) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter		Min	Max	Unit
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data Retention Only	1.5	—	V
V _{IH}	High-Level Input Voltage	V _{CC} = 1.65V to 1.95V	0.65 x V _{CC}	—	V
		V _{CC} = 2.3V to 2.7V	1.7	—	
		V _{CC} = 3V to 3.6V	2	—	
		V _{CC} = 4.5V to 5.5V	0.7 x V _{CC}	—	
V _{IL}	Low-Level Input Voltage	V _{CC} = 1.65V to 1.95V	—	0.35 x V _{CC}	V
		V _{CC} = 2.3V to 2.7V	—	0.7	
		V _{CC} = 3V to 3.6V	—	0.8	
		V _{CC} = 4.5V to 5.5V	—	0.3 x V _{CC}	
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage		0	V _{CC}	V
I _{OH}	High-Level Output Current	V _{CC} = 1.65V	—	-4	mA
		V _{CC} = 2.3V	—	-8	
		V _{CC} = 3V	—	-16	
		V _{CC} = 4.5V	—	-32	
I _{OL}	Low-Level Output Current	V _{CC} = 1.65V	—	4	mA
		V _{CC} = 2.3V	—	8	
		V _{CC} = 3V	—	16	
		V _{CC} = 4.5V	—	32	
Δt/ΔV	Input Transition Rise or Fall Rate	V _{CC} = 1.8V ± 0.15V, 2.5V ± 0.2V	—	20	ns/V
		V _{CC} = 3.3V ± 0.3V	—	10	
		V _{CC} = 5V ± 0.5V	—	5	
T _A	Operating Free-Air Temperature	—	-40	+125	°C

Note: 6. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V _{CC}	+40°C to +85°C		-40°C to +125°C		Unit
				Min	Max	Min	Max	
V _{OH}	High-Level Output Voltage	I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	—	V _{CC} - 0.1	—	V
		I _{OH} = -4mA	1.65V	1.2	—	0.95	—	
		I _{OH} = -8mA	2.3V	1.9	—	1.7	—	
		I _{OH} = -16mA	3V	2.4	—	2.2	—	
		I _{OH} = -24mA		2.3	—	2.0	—	
		I _{OH} = -32mA	4.5V	3.8	—	3.4	—	
V _{OL}	Low-Level Output Voltage	I _{OL} = 100μA	1.65V to 5.5V	—	0.1	—	0.1	V
		I _{OL} = 4mA	1.65V	—	0.45	—	0.70	
		I _{OL} = 8mA	2.3V	—	0.3	—	0.45	
		I _{OL} = 16mA	3V	—	0.4	—	0.60	
		I _{OL} = 24mA		—	0.55	—	0.80	
		I _{OL} = 32mA	4.5V	—	0.55	—	0.80	
I _I	Input Current	V _I = 5.5V or GND	0 to 5.5V	—	±5	—	±20	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 5.5V	0	—	±10	—	±20	μA
I _{CC}	Supply Current	V _I = 5.5V or GND, I _O = 0	1.65V to 5.5V	—	10	—	40	μA
ΔI _{CC}	Additional Supply Current	Input at V _{CC} - 0.6V	3V to 5.5V	—	500	—	5000	μA

Package Characteristics (@ $T_A = +25^\circ\text{C}$, $V_{CC} = 3.3\text{V}$, unless otherwise specified.)

Symbol	Parameter	Package	Conditions	Min	Typ	Max	Unit
C_I	Input Capacitance	Typical of All Packages	$V_{CC} = 3.3\text{V}$ $V_I = V_{CC}$ or GND	—	3.5	—	pF
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT26	(Note 7)	—	204	—	$^\circ\text{C}/\text{W}$
		SOT363		—	371	—	
		X2-DFN1410-6		—	430	—	
		X2-DFN1409-6		—	450	—	
		X1-DFN1010-6 (Type B)		—	495	—	
		X2-DFN1010-6		—	510	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT26	(Note 7)	—	52	—	$^\circ\text{C}/\text{W}$
		SOT363		—	143	—	
		X2-DFN1410-6		—	190	—	
		X2-DFN1409-6		—	225	—	
		X1-DFN1010-6 (Type B)		—	245	—	
		X2-DFN1010-6		—	250	—	

Note: 7. Test condition for all packages: Device mounted on FR-4 substrate PC board, 2oz copper with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $C_L = 30$ or 50pF (See Figure 1)

Parameter	From (Input)	To (Output)	$V_{CC} = 1.8\text{V}$ $\pm 0.15\text{V}$		$V_{CC} = 2.5\text{V}$ $\pm 0.2\text{V}$		$V_{CC} = 3.3\text{V}$ $\pm 0.3\text{V}$		$V_{CC} = 5\text{V}$ $\pm 0.5\text{V}$		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	0.5	8.6	0.5	4.4	0.5	4.1	0.5	3.2	ns

$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $C_L = 30$ or 50pF (See Figure 1)

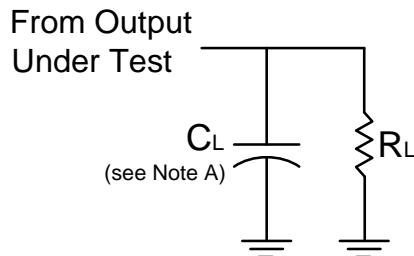
Parameter	From (Input)	To (Output)	$V_{CC} = 1.8\text{V}$ $\pm 0.15\text{V}$		$V_{CC} = 2.5\text{V}$ $\pm 0.2\text{V}$		$V_{CC} = 3.3\text{V}$ $\pm 0.3\text{V}$		$V_{CC} = 5\text{V}$ $\pm 0.5\text{V}$		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	0.5	10.8	0.5	5.5	0.5	5.1	0.5	4.0	ns

Operating Characteristics

$T_A = +25^\circ\text{C}$

Parameter	Test Conditions	$V_{CC} = 1.8\text{V}$		$V_{CC} = 2.5\text{V}$		$V_{CC} = 3.3\text{V}$		$V_{CC} = 5\text{V}$		Unit
		Typ	Typ	Typ	Typ	Typ	Typ	Typ	Typ	
C_{PD}	Power Dissipation Capacitance	f = 10MHz	17	19	20	21	21	21	21	pF

Parameter Measurement Information



V _{CC}	Inputs		V _M	C _L	R _L
	V _I	t _r /t _f			
1.8V ± 0.15V	V _{CC}	≤ 2ns	V _{CC} /2	30pF	1kΩ
2.5V ± 0.2V	V _{CC}	≤ 2ns	V _{CC} /2	30pF	500Ω
3.3V ± 0.3V	3V	≤ 2.5ns	1.5V	50pF	500Ω
5V ± 0.5V	V _{CC}	≤ 2.5ns	V _{CC} /2	50pF	500Ω

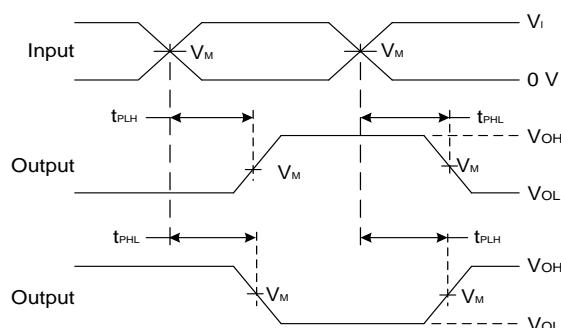
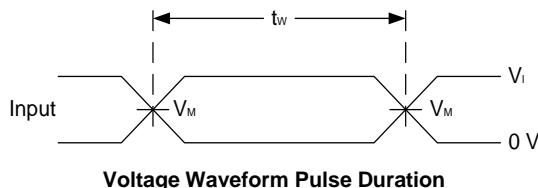
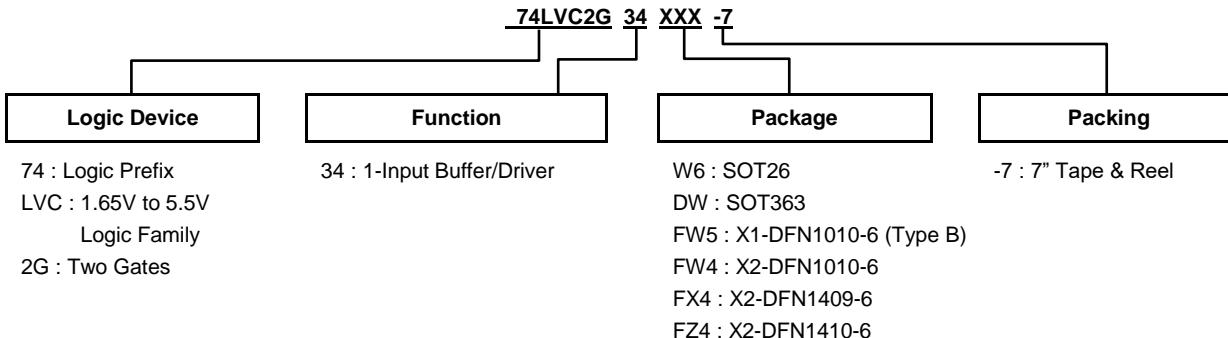


Figure 1. Load Circuit and Voltage Waveforms

Notes:

- A. Includes test lead and test apparatus capacitance.
- B. All pulses are supplied at pulse repetition rate ≤ 10MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{PD}.

Ordering Information



Part Number	Part Number Suffix	Package Code	Package (Note 8)	Package Size	Packing (Note 9)	
					Qty.	Carrier
74LVC2G34W6-7	-7	W6	SOT26	2.8mm x 2.2mm x 1.1mm 0.95mm Lead Pitch	3000	Tape & Reel
74LVC2G34DW-7	-7	DW	SOT363	2.0mm x 2.0mm x 1.1mm 0.65mm Lead Pitch	3000	Tape & Reel
74LVC2G34FW5-7	-7	FW5	X1-DFN1010-6 (Type B)	1.0mm x 1.0mm x 0.5mm 0.35mm Pad Pitch	5000	Tape & Reel
74LVC2G34FW4-7	-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35mm Pad Pitch	5000	Tape & Reel
74LVC2G34FX4-7	-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm x 0.9mm x 0.4mm 0.5mm Pad Pitch	5000	Tape & Reel
74LVC2G34FZ4-7	-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5mm Pad Pitch	5000	Tape & Reel

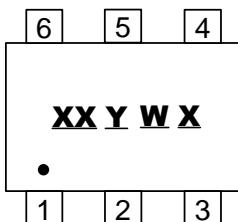
Notes:

- 8. Pad layout as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
- 9. The taping orientation is located on our website <https://www.diodes.com/assets/Packaging-Support-Docs/ap02007.pdf>.

Marking Information

(1) SOT26, SOT363

(Top View)

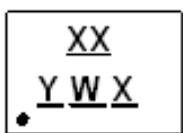


XX: Identification Code
Y: Year 0 to 9 (ex: 2 = 2022)
W: Week: A to Z: Week 1 to 26;
 a to z: Week 27 to 52; z Represents
 Week 52 and 53
X: A to Z: Internal Code

Part Number	Package	Identification Code
74LVC2G34W6-7	SOT26	Z7
74LVC2G34DW-7	SOT363	Z7

Marking Information (continued)

(2) X1-DFN1010-6 (Type B), X2-DFN1010-6, X2-DFN1409-6, X2-DFN1410-6

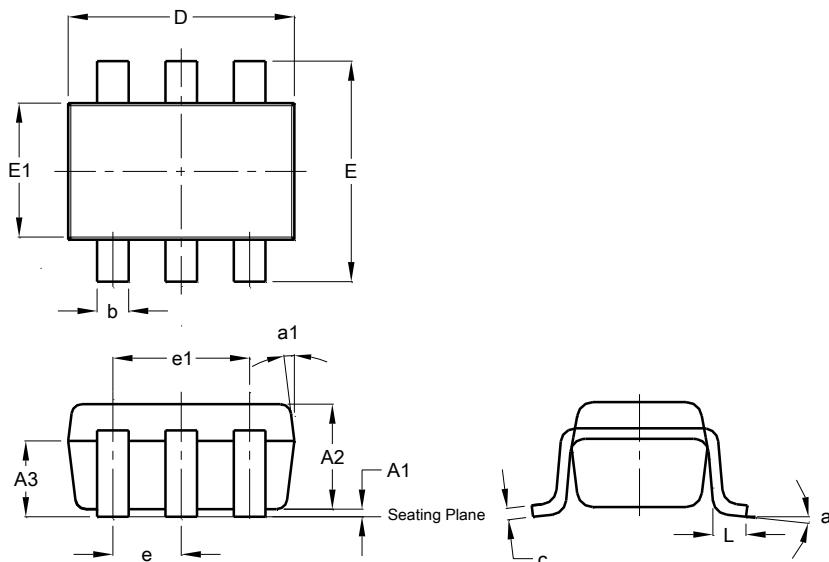
(Top View)XX: Identification CodeY: Year 0 to 9 (ex: 2 = 2022)W: Week: A to Z: Week 1 to 26;
a to z: Week 27 to 52; z Represents
Week 52 and 53X: A to Z: Internal Code

Part Number	Package	Identification Code
74LVC2G34FW4-7	X2-DFN1010-6	Z7
74LVC2G34FW5-7	X1-DFN1010-6 (Type B)	W7
74LVC2G34FX4-7	X2-DFN1409-6	X7
74LVC2G34FZ4-7	X2-DFN1410-6	Z7

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

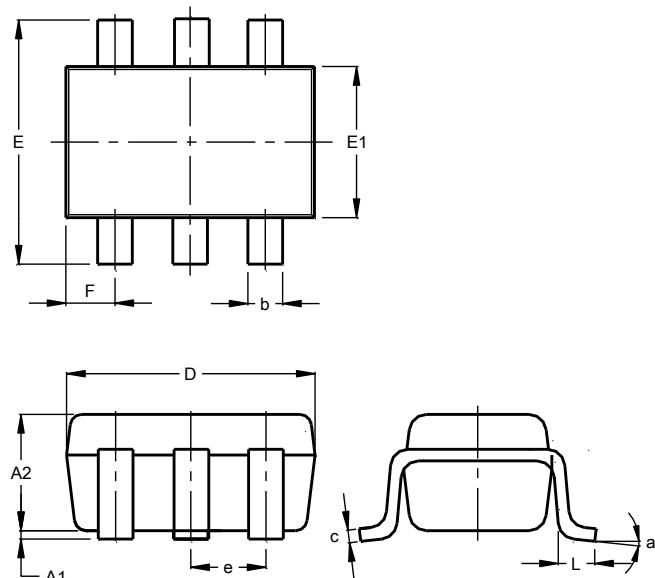
SOT26



SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°

All Dimensions in mm

SOT363



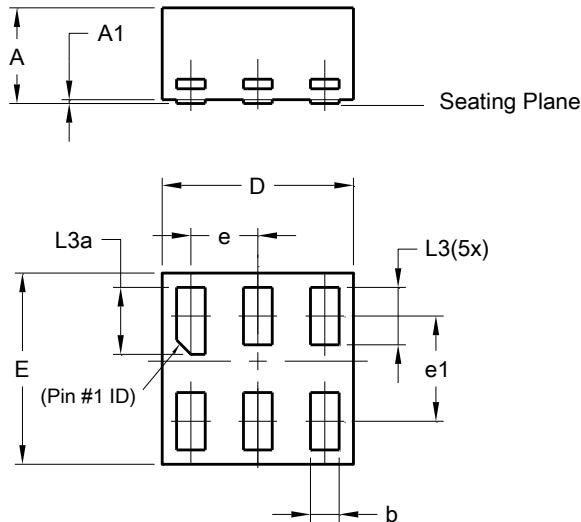
SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--

All Dimensions in mm

Package Outline Dimensions (continued)

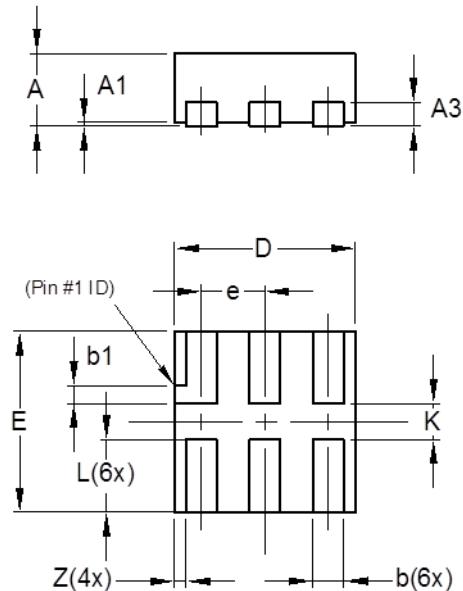
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1010-6 (Type B)



X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			

X2-DFN1010-6

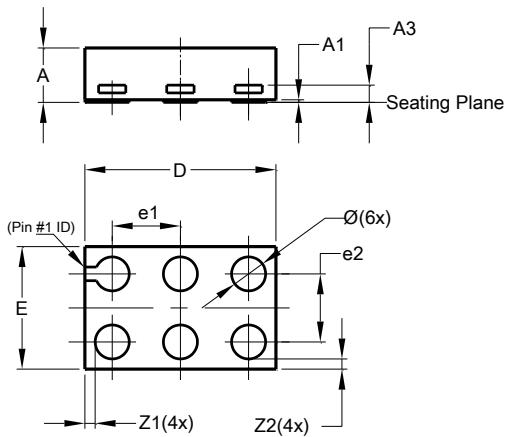


X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

Package Outline Dimensions (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

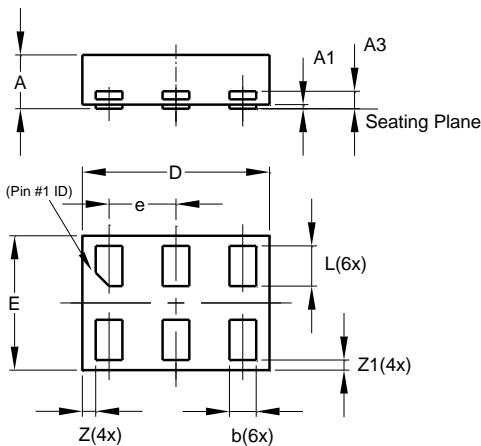
X2-DFN1409-6



X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
\emptyset	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075

All Dimensions in mm

X2-DFN1410-6



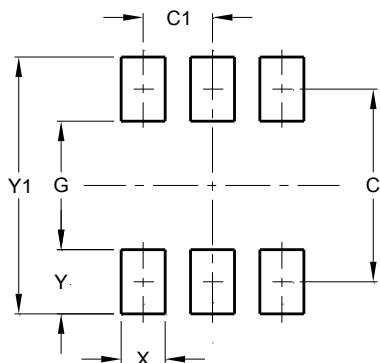
X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075

All Dimensions in mm

Suggested Pad Layout

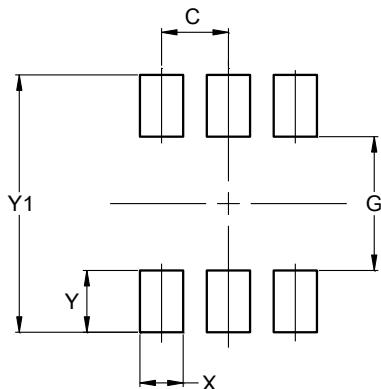
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



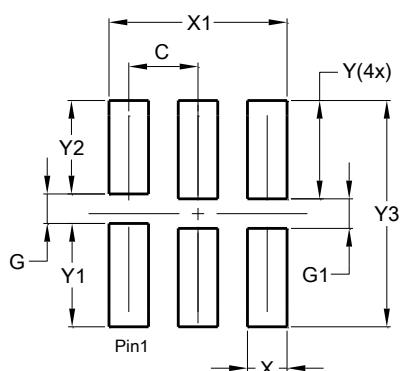
Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

SOT363



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

X1-DFN1010-6 (Type B)

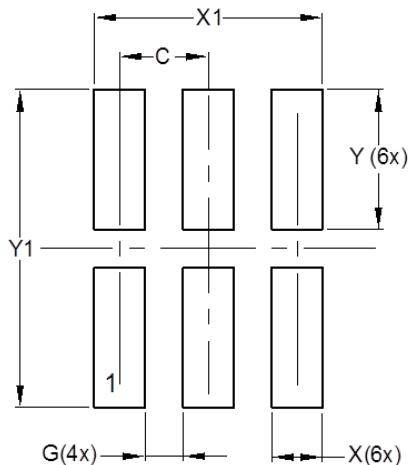


Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

Suggested Pad Layout (continued)

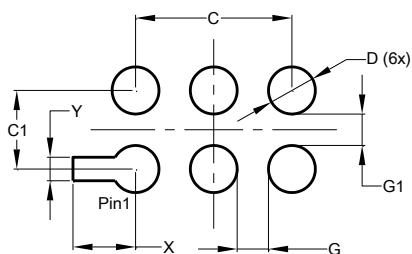
 Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6



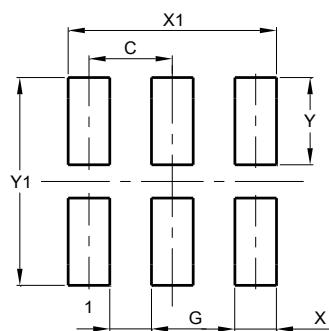
Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

X2-DFN1409-6



Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

Mechanical Data

SOT26

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ^(e3)
- Weight: 0.016 grams (Approximate)

SOT363

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ^(e3)
- Weight: 0.006 grams (Approximate)

X1-DFN1010-6 (Type B)

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.001 grams (Approximate)

X2-DFN1010-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.001 grams (Approximate)

X2-DFN1409-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.002 grams (Approximate)

X2-DFN1410-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.002 grams (Approximate)

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